

LGM100HF120S2F1A

1200V/100A Half Bridge in one-package

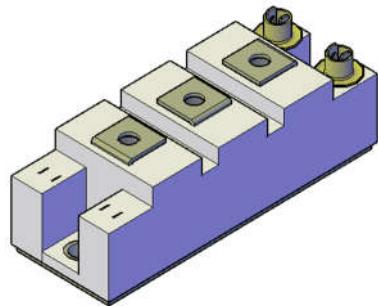
FEATURES

- V_{CEsat} with positive temperature coefficient
- Low switching losses
- Low inductance case
- Isolated copper baseplate using DBC technology

Preliminary Data

$V_{CES} = 1200V$

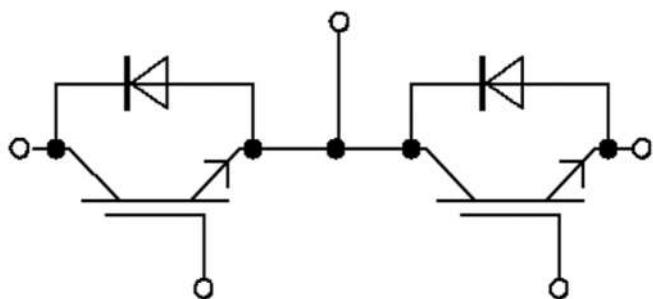
$IC \text{ nom} = 100A / ICRM = 200A$



APPLICATION

- Welding Machine
- Switching Mode Power Supplies

Equivalent Circuit Schematic



**IGBT, Inverter
Maximum Rated Values**

Parameter	Conditions	Symbol	Values		Units
Collector-emitter voltage	Tvj = 25°C	V _{CES}	1200		V
Continuous DC collector current	T _C = 100°C, Tvj max = 175°C	I _C	100		A
Repetitive peak collector current	t _P = 1 ms	I _{CRM}	200		A
Total power dissipation	T _C = 25°C, Tvj max = 175°C	P _{tot}	577		W
Gate-emitter peak voltage		V _{GE}	±20		V

Characteristic Values

Parameter	Conditions	Symbol	Values			Units
			Min.	Typ.	Max.	
Collector-emitter saturation voltage	I _C = 100A, V _{GE} = 15 V Tvj = 25°C	V _{CESat}		1.85		V
Gate threshold voltage	I _C = 1.5 mA, V _{CE} = V _{GE} Tvj = 25°C	V _{GTh}		5.7		V
Gate charge	V _{GE} = -15 / 15 V	Q _G		0.7		μC
Input capacitance	f = 1 MHz, Tvj = 25°C, V _{CE} = 25 V, V _{GE} = 0 V	C _{ies}		5.8		nF
Reverse transfer capacitance		C _{res}		0.21		nF
Collector-emitter cut-off current	V _{CE} = 1200 V, V _{GE} = 0 V, Tvj = 25°C	I _{CES}			1.0	mA
Gate-emitter leakage current	V _{CE} = 0 V, V _{GE} = 20 V, Tvj = 25°C	I _{GES}			200	nA
Turn-on delay time, inductive load	I _C = 100A, V _{CE} = 600 V V _{GE} = -15 / 15 V , RG = 10Ω Tvj = 25°C	t _{d on}		0.24		μs
Rise time, inductive load		t _r		0.12		μs
Turn-off delay time, inductive load		t _{d off}		0.32		μs
Fall time, inductive load		t _f		0.18		μs
Turn-on energy loss per pulse		E _{on}		9.78		mJ
Turn-off energy loss per pulse		E _{off}		7.44		mJ
Thermal resistance, junction to case	per IGBT	R _{thJC}			0.26	K/W
Thermal resistance, case to heatsink	per IGBT $\lambda_{\text{Paste}}=1 \text{ W}/(\text{m}\cdot\text{K})$ / $\lambda_{\text{grease}}=1 \text{ W}/(\text{m}\cdot\text{K})$	R _{thCH}		0.076		K/W
Temperature under switching conditions		Tvj op	-40		150	°C

Diode, Inverter
Maximum Rated Values

Parameter	Conditions	Symbol	Values		Units
Repetitive peak reverse voltage	$T_{vj} = 25^\circ\text{C}$	V _{RRM}	1200		V
Continuous DC forward current		I _F	100		A
Repetitive peak forward current	$t_p = 1 \text{ ms}$	I _{FRM}	200		A

Characteristic Values

Parameter	Conditions	Symbol	Values			Units
			Min.	Typ.	Max.	
Forward voltage	$I_F = 100 \text{ A}, V_{GE} = 0 \text{ V}$ $T_{vj} = 25^\circ\text{C}$	V _F		1.7		V
Peak reverse recovery current		I _{RR}		140		A
Recovered charge	$I_F = 100 \text{ A}, -dI_F/dt = 2400 \text{ A}/\mu\text{s}$ $V_R = 600 \text{ V}, V_{GE} = -15 \text{ V}$ $T_{vj} = 25^\circ\text{C}$	Q _{RR}		7		μC
Reverse recovery energy		E _{rec}		1.75		mJ
Thermal resistance, junction to case	per diode	R _{thJC}			0.52	K/W
Thermal resistance, case to heatsink	per diode $I_{paste} = 1 \text{ W}/(\text{m}\cdot\text{K}) / I_{grease} = 1 \text{ W}/(\text{m}\cdot\text{K})$	R _{thCH}		0.16		K/W
Temperature under switching conditions		T _{vj op}	-40		150	°C

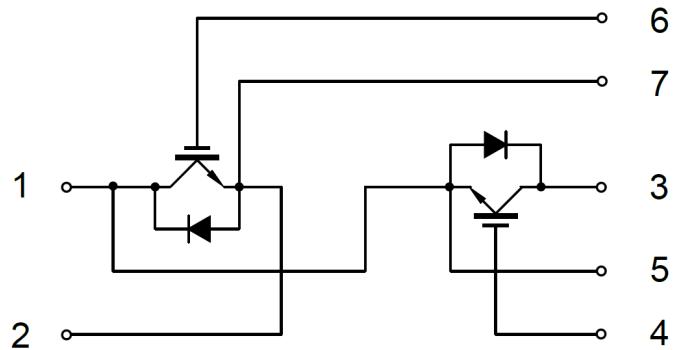
Module
Maximum Rated Values

Parameter	Conditions	Symbol	Values		Units
Isolation test voltage	RMS, f = 50 Hz, t = 1 min.	VISOL	2.5		kV
Internal isolation	basic insulation (class 1, IEC 61140)		Al ₂ O ₃		
Creepage distance	terminal to heatsink terminal to terminal		17 20		mm
Clearance	terminal to heatsink terminal to terminal		17 9.5		mm
Comparative tracking index		CTI	>200		

Characteristic Values

Parameter	Conditions	Symbol	Values			Units
			Min.	Typ.	Max.	
Stray inductance module and fixture		L _{sCE}		35		nH
Module lead resistance, terminals - chip	TC = 25°C, per switch	R _{CC+EE}		0.7		mΩ
Storage temperature		T _{stg}	-40		125	°C
Mounting force per clamp		F	3		5	N
Weight		G		164		g

Circuit diagram



Package outlines (mm)

